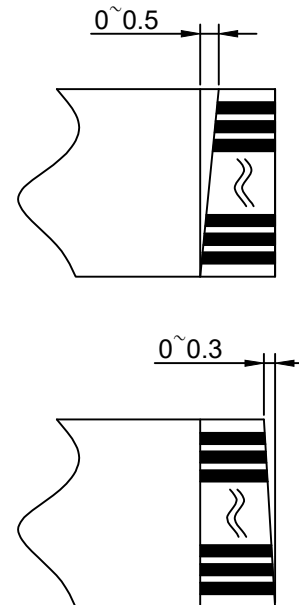
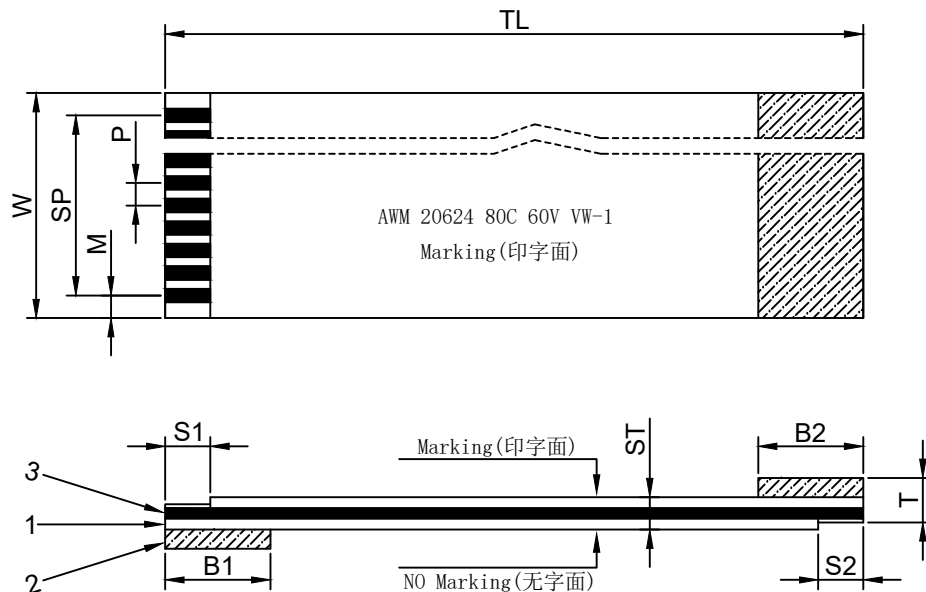


EDITION	SUMMARY OF CHANGES				ISSUE DATE
A0	新版发行				2026/01/12

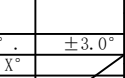


STRUCTURE (构造)				
NO.	ITEM (项目)	SPECIFICATION (规格)		
1	INSULATION (胶膜)	印字膜:通用版20624 (43μm)		
		白膜:80° C 60V (43μm)		
2	SUPPORTING TAPE (补强板)	225μm		Blue (蓝色)
3	CONDUCTOR (导体)	Thickness (厚度)	0.035	±0.005
		Width (宽度)	0.3	±0.03
4	CONDUCTOR (导体镀层)	PLATED (电镀)	锡Sn (1μm)	MIN
		PLATED (电镀)		

DIMENSION (尺寸)			
No. of conductors (导体数目)	N	(N) P	
Pitch (间距)	P	0.5	±0.05
Span (总间距)	SP	(N-1)*0.5	±0.05
Width (总宽度)	W	(N+1)*0.5	±0.08
Margin (边缘宽度)	M	0.5	±0.07
Total length (总长度)	TL	(TL)	±2.0
Insert Thickness (插接端厚度)	T	0.3	±0.03
Surface Thickness (线身厚度)	ST	0.12	±0.03
Strip Length (裸铜长度)	S1	4.0 4/3可定做	±0.5
	S2	4.0 4/3可定做	±0.5
Supporting Tape Length (补强板长度)	B1	8.0 8/6/5/4/可定做	±1.0
	B2	8.0 8/6/5/4/可定做	±1.0

技术要求:

- 1、保存环境: 温度15~25℃ 湿 度: 30~50RH%
- 2、产品符合RoHS 2.0标准

DESIGN:		Xiping Huang			广东国连电子有限公司			
CHECK:		Ke Tian			GUANGDONG GUOLIAN ELECTRONICS CO., LTD			
APPROVED:		Youquan Xu			TITLE:			
DIM		TOL	DIM	TOL	FFC CABLE B型			
X.		±0.25			PART NO.			
X. X		±0.20			0.5*NP*TL*B (4/4/8/8) (0.035*0.3)			
X. XX		±0.15			REV. A			
X. XXX					SCALE: N/A			
					UNIT:	SHEET:		
					mm	1/1		